



Statement of Materials, Construction

8L-SOICN -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.02426	Cu	7440-50-8	0.02364	31.87233	97.43
				Fe	7439-89-6	0.00057	0.76876	2.35
				Pb	7439-92-1	0.00001	0.00981	0.03
				P	7723-14-0	0.00002	0.02715	0.08
				Zn	7440-66-6	0.00003	0.03598	0.11
2	Die	Silicon Chip	0.00263	Si	7440-21-3	0.00262	3.52865	99.50
3	Die attach material	Conductive Epoxy	0.00113	Epoxy resin	Proprietary	0.00017	0.22856	15.00
				Silver	7440-22-4	0.00090	1.21137	79.50
				Aromatic Amine	Proprietary	0.00006	0.08381	5.50
4	Wire	Gold	0.00030	Au	7440-57-5	0.00030	0.40449	99.99
5	Lead Finish	Alloy	0.00146	Pb	7439-92-1	0.00015	0.19687	10.00
				Sn	7440-31-5	0.00131	1.77184	90.00
				Fused Silica	60676-86-0	0.03581	48.29377	80.70
6	Encapsulation	Epoxy Resin	0.04438	Epoxy resin	Proprietary	0.00444	5.98436	10.00
				Phenol Resin	Proprietary	0.00067	0.89765	1.50
				Phenol Novolac	9003-35-4	0.00133	1.79531	3.00
				Antimony trioxide	1309-64-4	0.00089	1.19687	2.00
				Brominated Epoxy resin	68541-56-0	0.00111	1.49609	2.50
				Carbon Black	1333-86-4	0.00013	0.17953	0.30
				Total Package weight			0.07416	

Note: Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit	(aximum Allowable Limit (wt %)
Lead	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%